



Investor Relations

NEXTIN, Inc.

Next Inspection Solutions for Semiconductor Applications

November 18th, 2024

Chris Park / CEO

NEXTIN

ECRC
EXCELLENT
CORPORATION R&D CENTER



Hidden Champion 100
Materials • Components • Equipment

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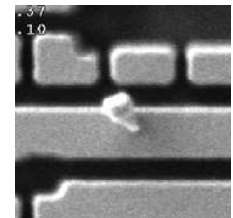
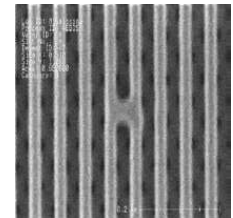
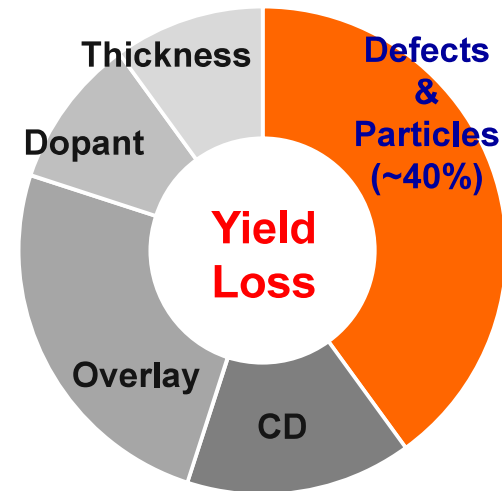
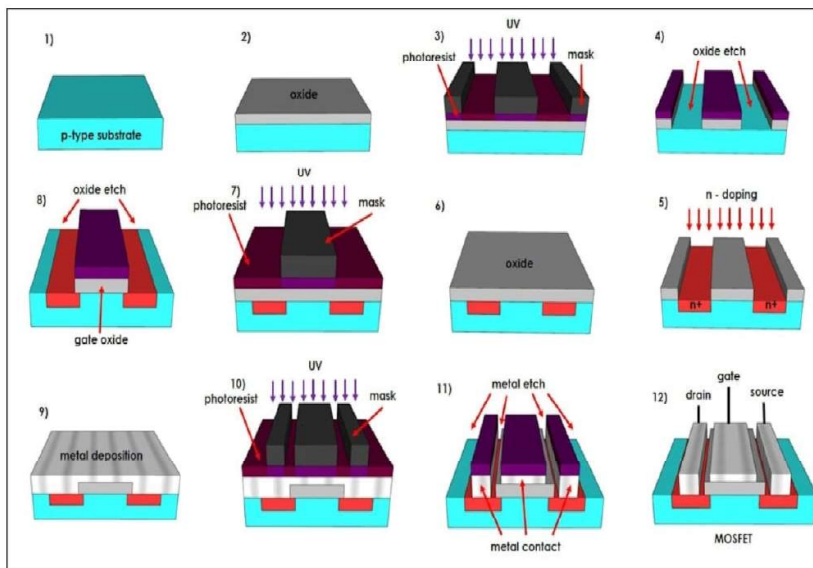


Market Analysis

NEXTIN brings Competition into the Wafer Inspection Market !!!

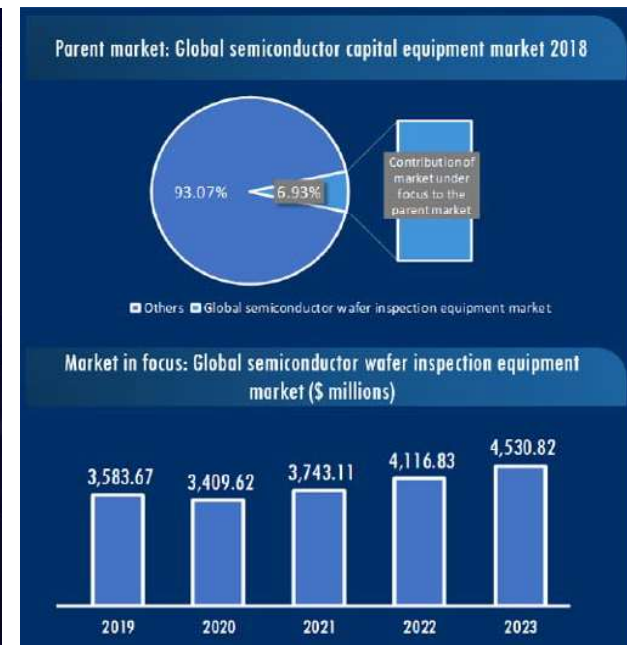
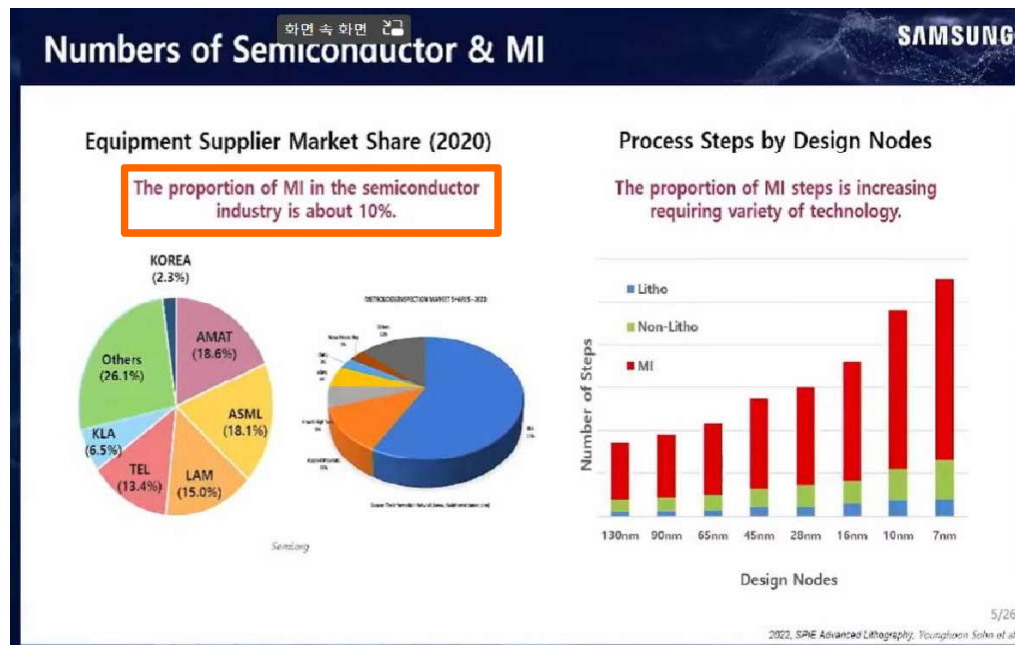
Wafer Inspection Process

- Fabrication of semiconductor devices has 3,000+ unit process such as lithography, etch, film deposition, ion implantation,
- Wafer inspection process is detecting pattern defects and particles which cause yield loss of device fabrication processes



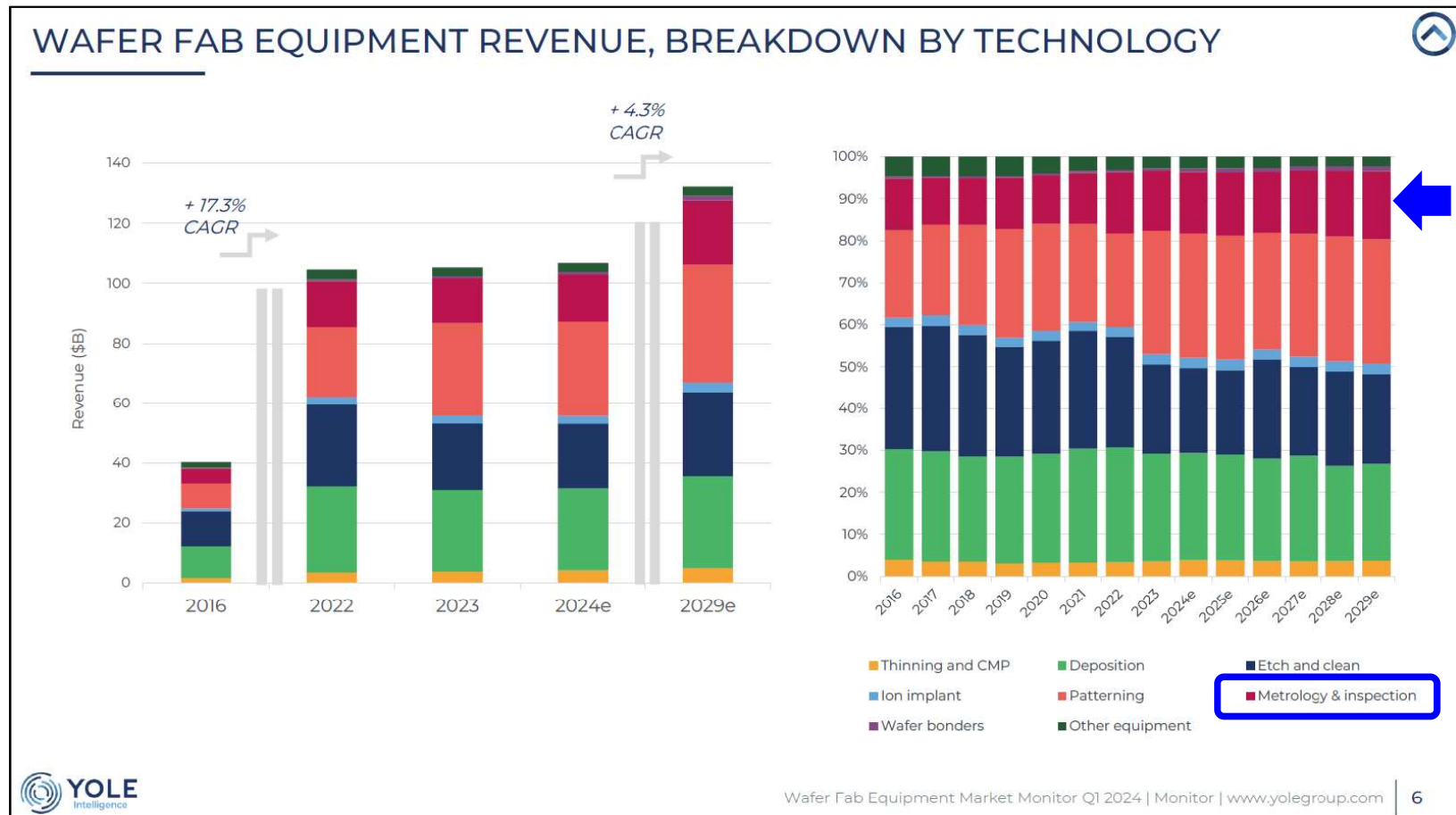
Wafer Inspection Process(2)

- Fabrication of advanced devices requires inspection process more and more
- Metrology & Inspection tool market size: 10% of Fab CAPEX @ Samsung
- Optical Inspection Tool Market Size: 5.5% of Fab CAPEX(Technavio Report 2019)



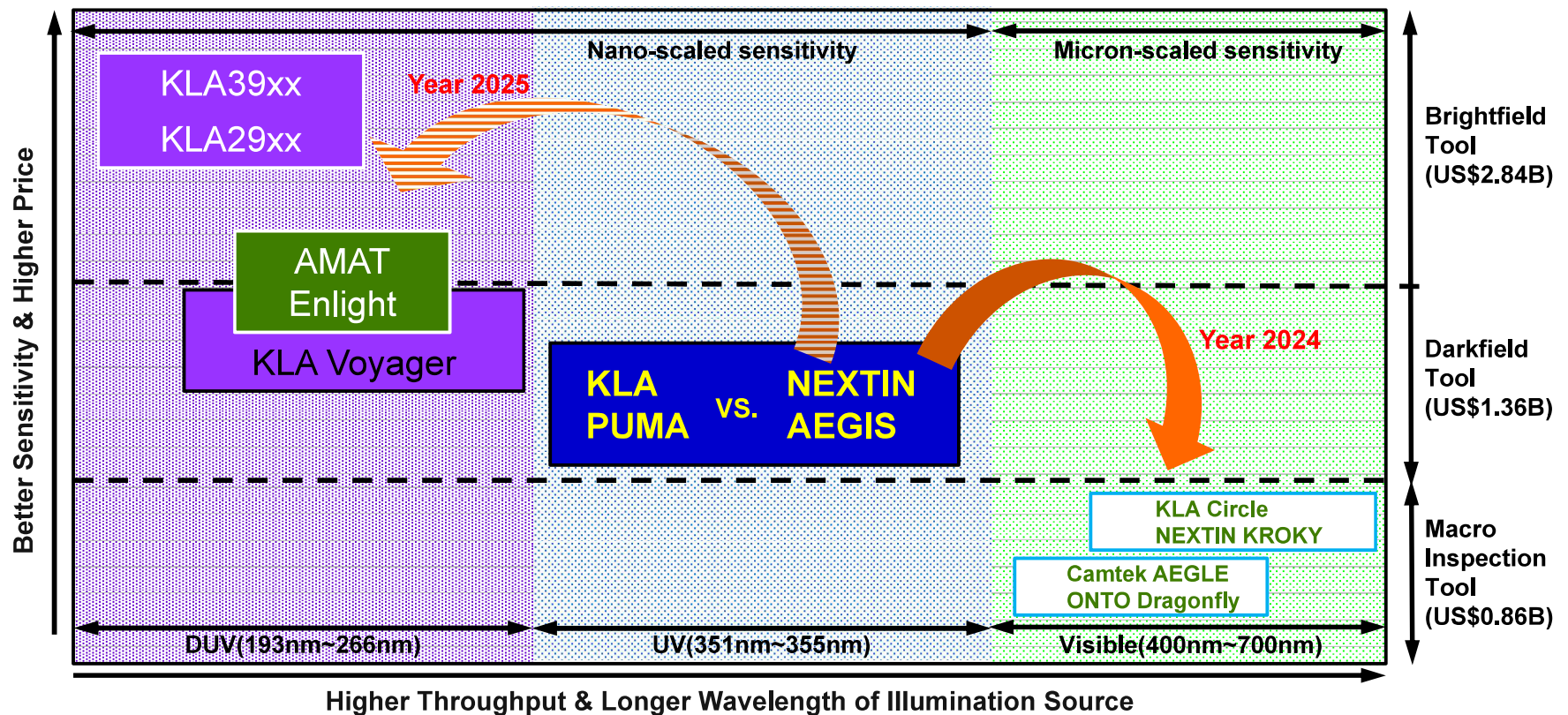
Importance of Wafer Inspection

The capital spending for MI tools is getting more and more!!!



Optical P-Wafer Inspection Tools

- Wafer fabs execute mix-and-match strategy between tools and suppliers
 - BF, DF and Macro tools have its own advantages and applications
 - Suppliers have its own technology and strengths in defect detection



NEXTIN Products

NEXTIN brings Competition into the Wafer Inspection Market !!!

AEGIS Evolution (DF Tool)

Cost-effective solution over the competitor !!!



AEGIS-III
(Higher X-put & New IP Engine)
2022



AEGIS-II
(Higher Performance Optics)
2020



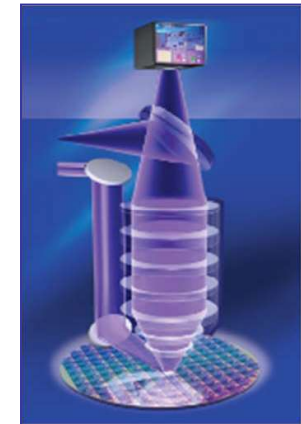
AEGIS-DP
(New IP Engine)
2018



AEGIS-XT
(Higher X-put)
2016

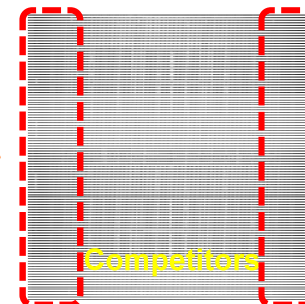
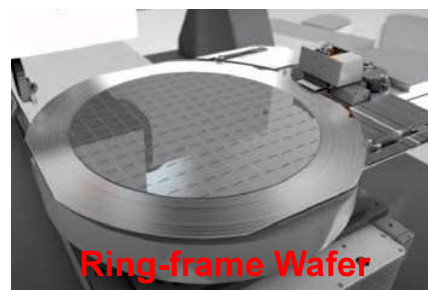
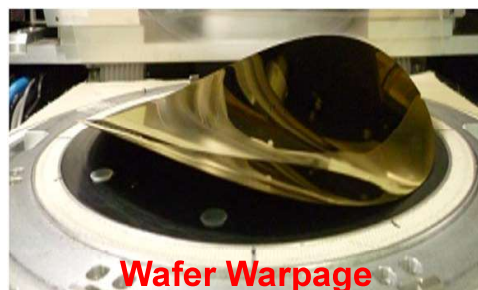
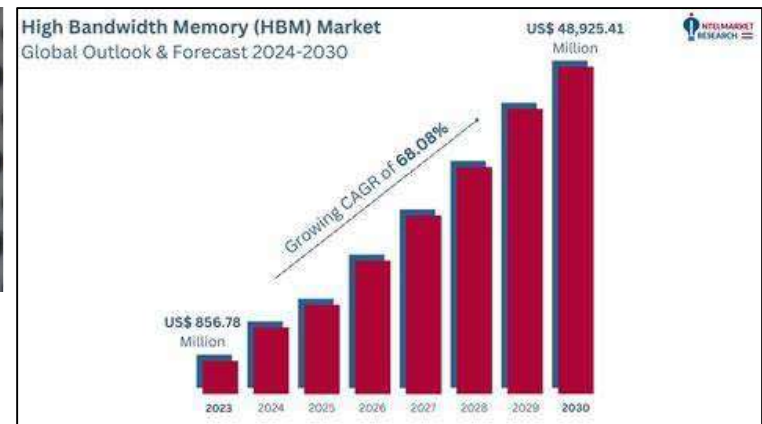
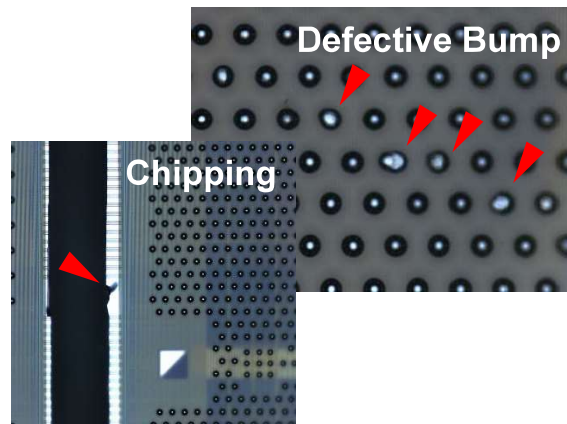


AEGIS
(2-Dim. Imaging System)
2014

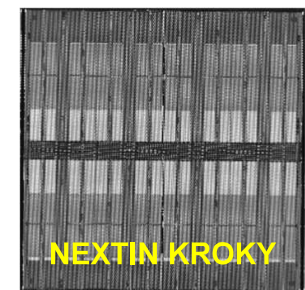


KROKY for HBM (Macro Tool)

- Advanced HBM gets bigger warpage than depth-of-focus (optical detection limit)
- KROKY resolves the difficulty with patented optic technology and algorithm
- KROKY is the only solution over competitors at competitive price !!!



VS.



IRIS for 3D Process

- Moore's Law keeps going on lateral scaling with vertical stacking – 3D Memory
- It requires paradigm shift in inspection technology – surface to buried defects
- Intel and NEXTIN presented new 3-dim. inspection technology at SPIE 2021
- IRIS is the only solution for very highly stacking processes !!!

Comparative near infrared through-focus scanning optical microscopy for 3D memory subsurface defect detection and classification

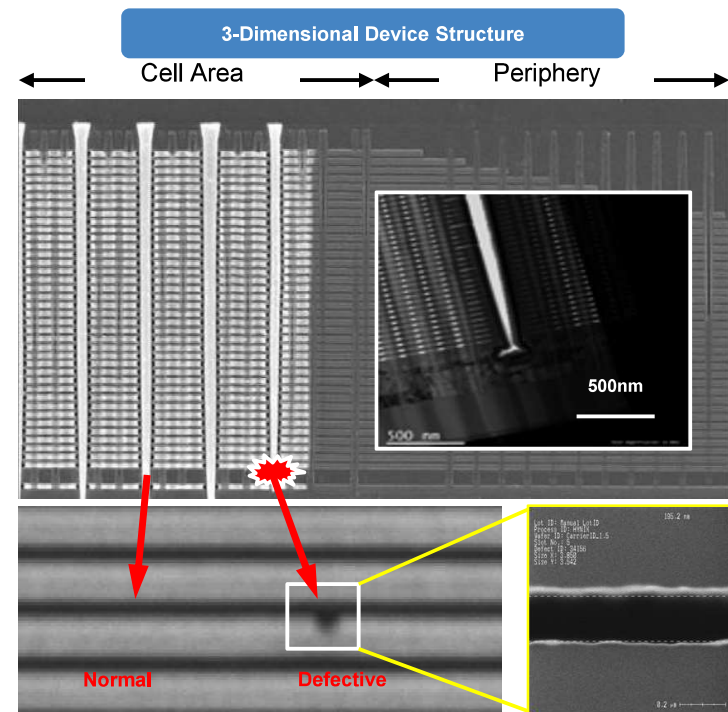
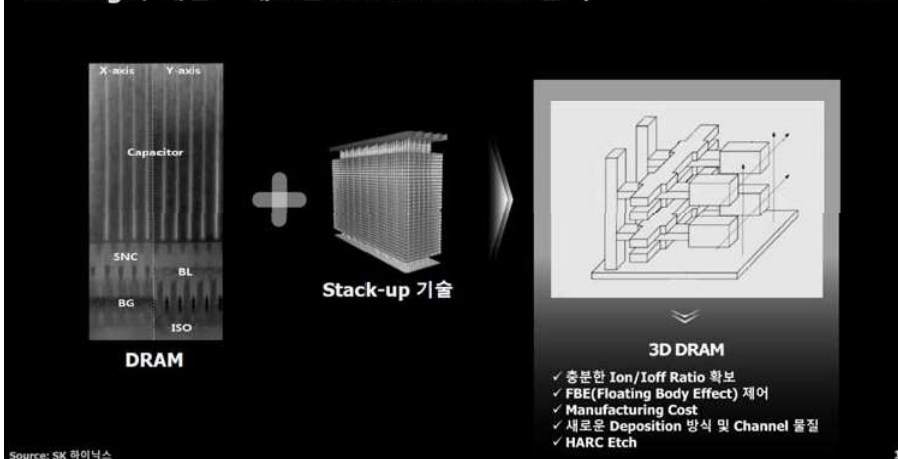
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Scaling의 대안 – 새로운 Tech. Platform 준비



ResQ for EUV Process

- Even weak electrostatic charges cause yield killing defects at <10nm design node
- Buried electrostatic charges should be removed before critical processes
- ResQ newly adds up electrostatic charge removal process at advanced process !!!

ResQ™
Wafer Electrostatic Charge Removal System

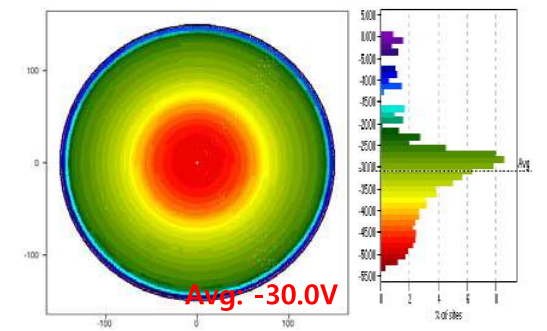
ESD-induced Issues

Removal Process of Embedded Charges

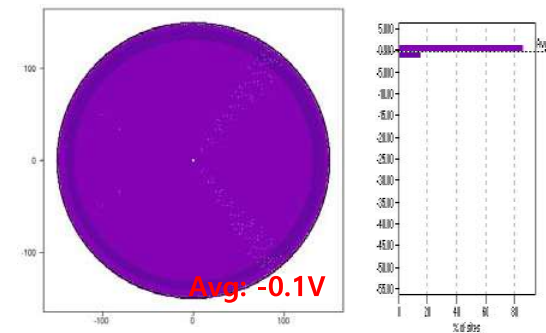
Benefit of Removing Embedded Charges

Enhancement of EUV Process Yield & Improvement of CD-SEM Resolution and Etch Profile by Removing Surface and Embedded Electric Charges in Film Stacks

NEXTIN
www.nextinsol.com



ResQ



Business Strategy

NEXTIN brings Competition into the Wafer Inspection Market !!!

Business Strategy

- Keep releasing next generation models on time: AEGIS-IV in 2025
- Secure the existing customers with localization in China
 - 无锡纳科鑫科技有限公司:
 - Production start: KROKY(Q3 2025) & AEGIS (Q1 2026)
- Engage with new customers: HHG, Intel, Micron, Kioxia, SONY, Infineon, GF, ..

- Make more success stories & value @ top-tier customer: KROKY, IRIS & ResQ
- Fan out with the success stories to other customers
- Keep developing next generation models to maintain performance gaps



Thanks you !!!

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